

SUBMINIATURE SOLID STATE LAMP

Part Number: AM27YC09 Yellow

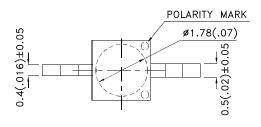
Features

- Subminiature package.
- Z-Bend lead.
- Long life solid state reliability.
- Low package profile.
- Package :1000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

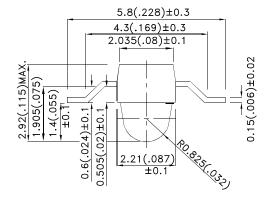
Description

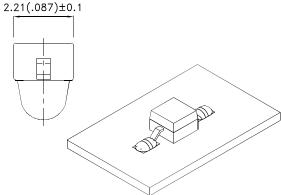
The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

Package Dimensions









- All dimensions are in millimeters (inches).
 Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
- 5. The device has a single mounting surface. The device must be mounted according to the specifications.

SPEC NO: DSAD1333 **REV NO: V.8** DATE: APR/14/2011 PAGE: 1 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: J.Yu ERP: 1202000439

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		,	Min.	Тур.	201/2
AM27YC09	Yellow (GaAsP/GaP)	Water Clear	20	50	20°

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Yellow	590		nm	IF=20mA
λD [1]	Dominant Wavelength	Yellow	588		nm	I==20mA
Δλ1/2	Spectral Line Half-width	Yellow	35		nm	IF=20mA
С	Capacitance	Yellow	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Yellow	2.1	2.5	V	I==20mA
lR	Reverse Current	Yellow		10	uA	V _R =5V

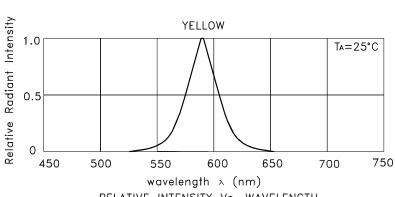
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Yellow	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	140	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

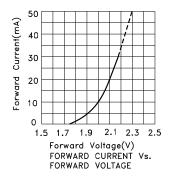
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

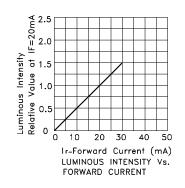
DATE: APR/14/2011 SPEC NO: DSAD1333 **REV NO: V.8** PAGE: 2 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: J.Yu ERP: 1202000439

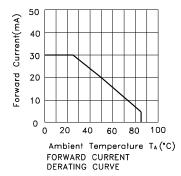


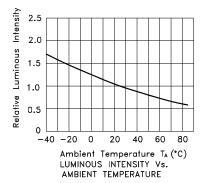
RELATIVE INTENSITY Vs. WAVELENGTH

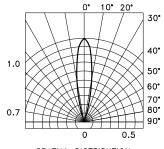
Yellow **AM27YC09**











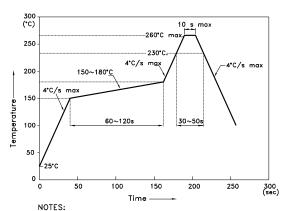
SPATIAL DISTRIBUTION

SPEC NO: DSAD1333 **REV NO: V.8** DATE: APR/14/2011 PAGE: 3 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: J.Yu ERP: 1202000439

AM27YC09

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



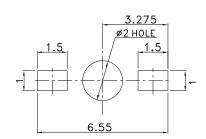
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

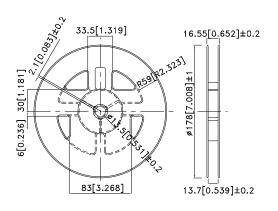
 3.Number of reflow process shall be 2 times or less.

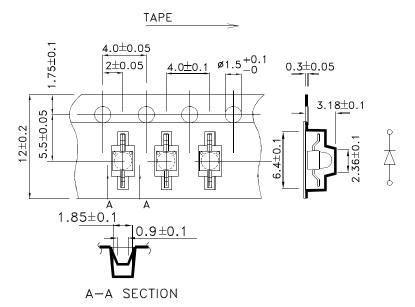
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units : mm)

Reel Dimension

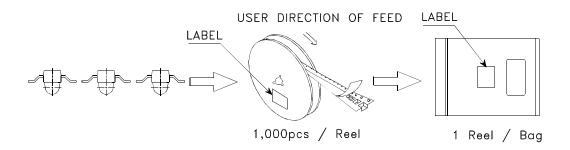


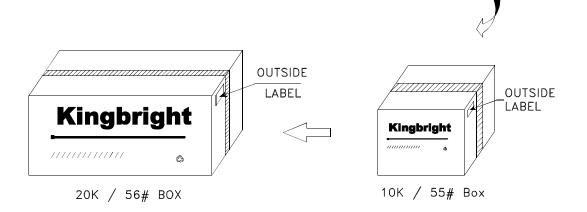


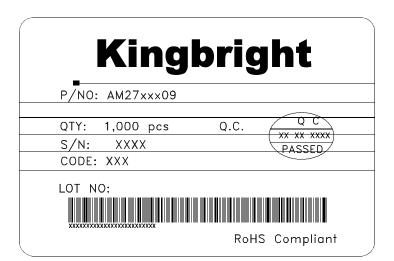
SPEC NO: DSAD1333 **REV NO: V.8** DATE: APR/14/2011 PAGE: 4 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: J.Yu ERP: 1202000439

PACKING & LABEL SPECIFICATIONS

AM27YC09







SPEC NO: DSAD1333 APPROVED: WYNEC REV NO: V.8 CHECKED: Allen Liu DATE: APR/14/2011 DRAWN: J.Yu PAGE: 5 OF 5 ERP: 1202000439